

1                   AMENDMENTS TO THE CLAIMS

2                   Please amend the claims of the present application as set forth below. In  
3                   accordance with the PTO's revised amendment format, a detailed listing of all  
4                   claims has been provided. A status identifier is provided for each claim in a  
5                   parenthetical expression following each claim number. Changes to the claims are  
6                   shown by strikethrough (for deleted matter) or underlining (for added matter).

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8                   Claims 70-75, 77, 80-83, 85-86 and 89-97 were pending at the time of the  
9                   Office Action.

10                  Claims 89 and 90 were previously withdrawn from consideration.

11                  Claims 70-75, 77, 80-83, 85-86 and 91-96 are rejected.

12                  Claim 97 is objected to.

13                  Claims 96 and 97 are amended by the current response.

14                  No claims are canceled by the current response.

15                  Accordingly, claims 70-75, 77, 80-83, 85-86 and 91-97 remain pending.

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17                  68. (previously canceled)

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19                  69. (previously canceled)

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21                  70. (previously amended)      The chip package of claim 74, further  
22                   comprising a flexible insert residing between the lead and the first side of the  
23                   packaging material, wherein the flexible insert supplies spring force when the lead  
24                   is compressed.

1           71. (previously amended) The chip package of claim 70, wherein  
2 the flexible insert is cylindrical.

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4           72. (previously added) The chip package of claim 71, wherein the  
5 flexible insert is a compliant material.

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7           73. (previously added) The chip package of claim 72, wherein the  
8 compliant material is an elastomer.

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10          74. (previously amended) The chip package of claim 91, wherein  
11 the lead is substantially C-shaped.

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13          75. (previously added) The chip package of claim 74, wherein the lead  
14 is compressible.

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16          76. (previously canceled)

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18          77. (previously amended) The chip package of claim 91, further  
19 comprising a pin extending from the packaging material to guide the chip package  
20 in the base.

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22          78. (previously canceled)

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24          79. (previously canceled)

1       80. (previously amended)     The chip package of claim 91, wherein  
2 the lead comprises beryllium-copper.

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4       81. (previously amended)     The chip package of claim 91, wherein  
5 the packaging material is comprised of a flexible material.

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7       82. (previously added)     The chip package of claim 81, wherein the  
8 flexible material supplies spring force when the lead is compressed.

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10      83. (previously amended)     The chip package of claim 91, wherein  
11 the packaging material comprises silicone rubber.

12      84. (previously canceled)

13      85. (previously amended)     The chip package of claim 91, further  
14 comprising an integrated circuit disposed in the packaging material.

15      86. (previously amended)     The chip package of claim 91, wherein  
16 the chip is flexible.

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18      87. (previously canceled)

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20      88. (previously canceled)

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22      89. (previously withdrawn)

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2 90. (previously withdrawn)

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4 91. (previously added) A chip package comprising:  
5 packaging material having a first side;  
6 a flexible lead extending from the first side; and  
7 a clip extending from the packaging material.

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9 92. (previously added) The chip package of claim 70, wherein the lead  
10 is compressible.

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12 93. (previously added) The chip package of claim 74 furthermore  
13 comprising an indentation; and wherein the lead extends into the indentation.

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15 94. (previously added) The chip package of claim 74 furthermore  
16 comprising an indentation; and wherein the lead extends into the indentation when  
17 the lead is compressed.

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19 95. (previously added) The chip package of claim 91, wherein the clip  
20 is integral with the packaging material.

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22 96. (currently amended) The chip package of claim 91, wherein  
23 the chip package is an assembly that comprises the clip and the packaging  
24 material, the clip and the packaging material each being attached to one another  
25 ~~separate from the other~~.

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2 97. (currently amended) A system comprising the chip package of  
3 claim 68 91 and a base unit, the base unit comprising a slotted guide; and the chip  
4 package further comprising a pin configured to be received by the slotted guide.

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